

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L3	1095	(chip ic integrated semiconductor) and (solder with (bump\$6 ball\$6)) and ((pad contact) with (protru\$8 core stud wire))	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/21 09:18
L4	189	L3 and (solder with (bath molten liquid melt\$6 fus\$6 wave reflow\$6))	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/21 09:18
L5	752	(chip ic integrated semiconductor) same (solder with (bump\$6 ball\$6)) same ((pad contact) with (protru\$8 core stud wire)) same (solder with (bath molten liquid melt\$6 fus\$6 wave reflow\$6))	US-PGPUB; USPAT	OR	ON	2005/10/21 15:22
L6	267	L5 same (interconnect\$8 passivat\$6 metallurg\$6 metali?6 metalli?6 ubm bum)	US-PGPUB; USPAT	OR	ON	2005/10/21 10:30
L7	32	("4067104" "4661192" "4752027" "4875618" "5060843" "5071787" "5090119" "5186381" "5485949" "5492863" "5496775" "5508561" "5550083" "5569963" "5579573" "5641113" "5650667").PN. OR ("5908317").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/10/21 11:39
L8	84	("3531852" "3680198" "4494688" "4693770" "4749120" "4784972" "4876221").PN. OR ("5071787").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/10/21 11:55
L10	73	((chip ic integrated semiconductor) and (solder with (bump\$6 ball\$6)) and ((pad contact) with (protru\$8 core stud wire)) and (solder with (bath molten liquid melt\$6 fus\$6 wave reflow\$6))).clm.	US-PGPUB	OR	ON	2005/10/21 15:23
S1	2744	438/613.cc1s. 438/614.cc1s. 438/615.cc1s. 228/180.22.cc1s.	US-PGPUB; USPAT	OR	OFF	2005/10/19 11:49
S2	251	438/615.cc1s.	US-PGPUB; USPAT	OR	OFF	2005/10/19 14:09
S3	2	wo-9616442-\$ did.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/10/19 12:06
S4	5	"6043985".pn. "6337445".pn. "6395983".pn. "6440835".pn. "6454159".pn.	US-PGPUB; USPAT	OR	OFF	2005/10/19 15:45

S5	1769	S1 and (chip ic integrated semiconductor) and solder and ((pad contact) same (bump\$6 protru\$8 core stud wire))	US-PGPUB; USPAT	OR	ON	2005/10/19 15:49
S6	1126	S1 and ((chip ic integrated semiconductor) same solder same ((pad contact) with (bump\$6 protru\$8 core stud wire)))	US-PGPUB; USPAT	OR	ON	2005/10/19 15:51
S8	1095	(chip ic integrated semiconductor) and (solder with (bump\$6 ball\$6)) and ((pad contact) with (protru\$8 core stud wire))	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/19 15:55
S10	751	(chip ic integrated semiconductor) same (solder with (bump\$6 ball\$6)) same ((pad contact) with (protru\$8 core stud wire)) same (solder with (bath molten liquid melt\$6 fus\$6 wave reflow\$6))	US-PGPUB; USPAT	OR	ON	2005/10/19 15:58
S12	2749	438/613.ccls. 438/614.ccls. 438/615.ccls. 228/180.22.ccls.	US-PGPUB; USPAT	OR	OFF	2005/10/20 15:12
S13	308	S12 and ((chip ic integrated semiconductor) same (solder with (bump\$6 ball\$6)) same ((pad contact) with (protru\$8 core stud wire)))	US-PGPUB; USPAT	OR	ON	2005/10/20 15:12